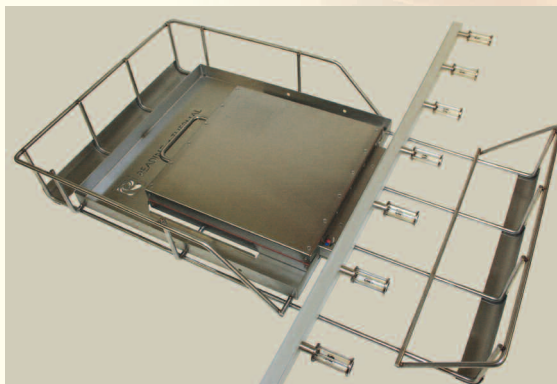
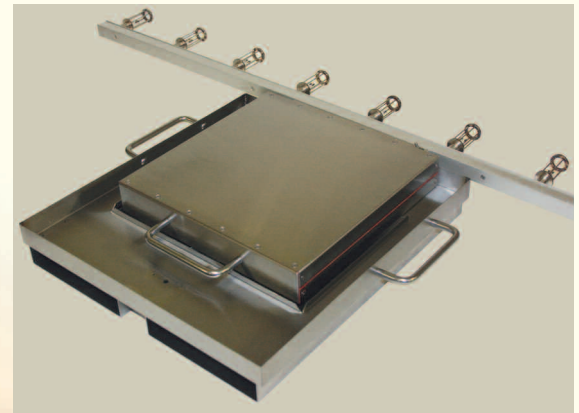




Bread & Bun Profiling Solutions

Specialized Carrier for Endless Conveyor Ovens (e.g. BakeTech)

Tray Style Carrier for SCORPION® 2 Equipment provides easy loading and unloading on endless conveyors. The carrier, with SCORPION® 2, is inserted into the product flow replacing a bread or bun pan. Stainless Steel Magnetic Base Tray 406mm (16") wide x 356mm (14") long x 51mm (2") high accommodates all SCORPION® 2 Equipment.

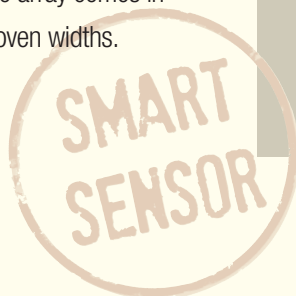
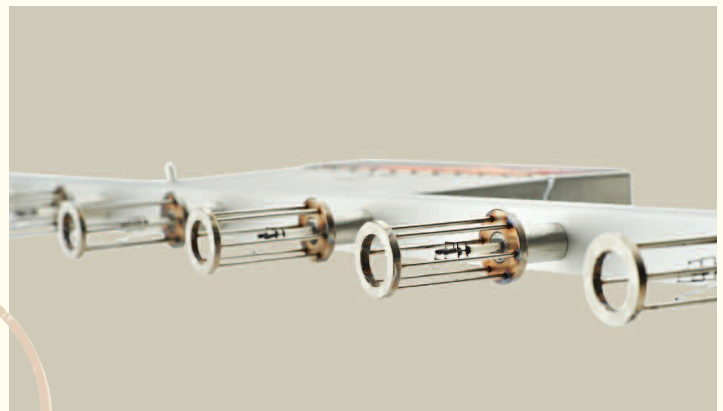


Specialized Carrier for Tray and Grid Conveyor Ovens (e.g. AMF, Turkington)

Basket Style Carrier for SCORPION® 2 Equipment provides easy loading and unloading on tray and grid conveyors. The carrier, with SCORPION® 2, is inserted into the product flow replacing a bread or bun pan. Stainless Steel Wire Frame Basket 381mm (15") wide x 660mm (26") long x 102mm (4") high accommodates all SCORPION® 2 Equipment.

Temp+Airflow Sensor Array

Designed to simultaneously profile temperature and airflow across the width of large tray and grid conveyor ovens. Array contains 9 Temp+Airflow sensors spaced evenly across the length of an aluminum bar. The array comes in 3 sizes to match the most popular bread oven widths. Custom sizes are available.



Pan+Dough Probe

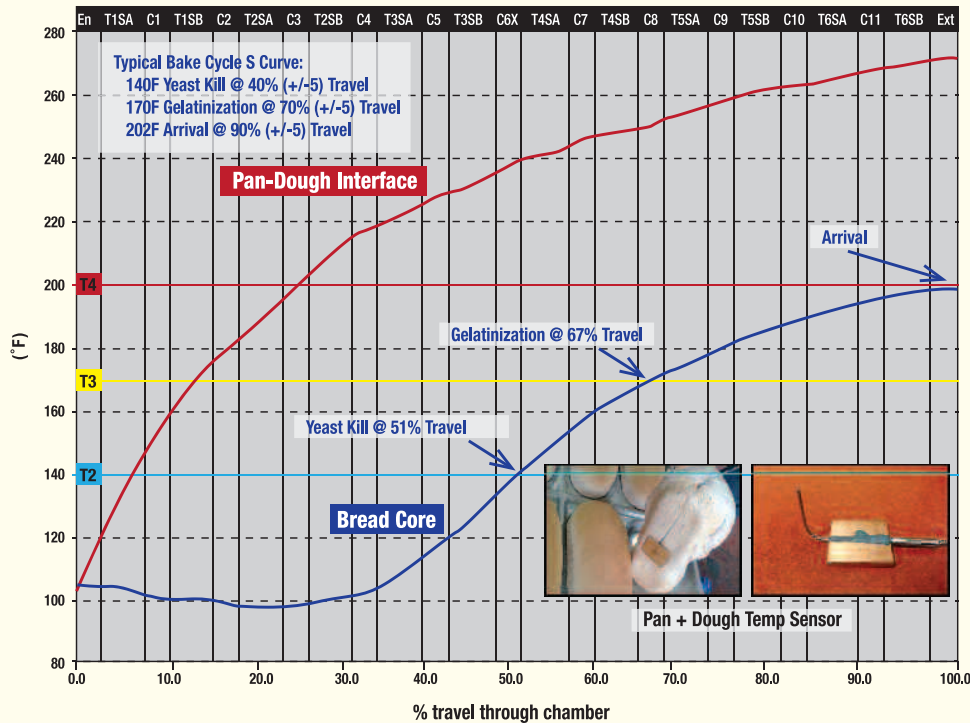
This dual probe unit is placed under the bread or bun dough simultaneously capturing the pan/dough interface temperature and the dough core temperature. The copper spade is pressed against the pan by the weight of the dough, measuring the critical pan/dough interface temperature. The vertical stainless steel probe penetrates the dough to a fixed distance from the pan, measuring the dough core temperature used to produce the Bake Cycle S-Curve. The Pan+Dough Probe provides accurate repeatable results unattainable with hand-placed thermocouples. It connects to the Temperature Interface device which can accommodate 5 Pan+Dough Probes.



Bake Cycle S-Curve Analysis

Bakers rely on Bake Cycle S-Curve Analysis to optimize the baking profile. This analysis provides critical insight needed to make adjustments to ingredients, bake time, and zone temperature settings. SCORPION® Software Version 8 (SV8) automatically calculates the three key S-Curve data points: Yeast Kill, Gelatinization and Arrival.

Pan-Dough Interface Temp & Bread Core Temp



READING THERMAL